Designator	Quantity	Value	Description	PackageReference	PartNumber	Manufacturer	Alternate PartNumber	Alternate Manufacturer
!PCB	1		Printed Circuit Board		PWR582	Any	-	-
C1	1	0.47uF	Capacitor, Ceramic Chip, 10V, X5R, +/-10%	402	C1005X5R1A474K050B B	TDK		
C2	1	1.0uF	Capacitor, Ceramic Chip, 16V, X5R, +/-10%	402	C1005X5R1C105K050B C	TDK		
J1, J4, J6, J7	4	ED555/2DS	Terminal Block, 2-pin, 6-A, 3.5mm	0.27 x 0.25 inch	ED555/2DS	OST		
J2, J3, J8, J9	4	PEC03SAAN	Header, Male 3-pin, 100mil spacing,	0.100 inch x 3	PEC03SAAN	Sullins		
J5	1	ED555/3DS	Terminal Block, 3-pin, 6-A, 3.5mm	0.41 x 0.25 inch	ED555/3DS	OST		
J10	1	22-05-3041	Header, Friction Lock Ass'y, 4-pin Right Angle,	0.400 x 0.500 inch	22-05-3041	Molex		
J11	1	PEC02SAAN	Header, Male 2-pin, 100mil spacing,	0.100 inch x 2	PEC02SAAN	Sullins		
LBL1	1			PCB Label 0.650"H x 0.200"W	THT-14-423-10	Brady		
R1	1	0.010	Resistor, Power Metal Strip, 0.25W, 1%	805	WSL0805R0100FEA1	Vishay		
R2	1	1.8Meg	RES, 1.8Meg ohm, 5%, 0.063W, 0402	0402	CRCW04021M80JNED	Vishay-Dale		
R3, R4, R5	3	5.1k	RES, 5.1k ohm, 5%, 0.063W, 0402	0402	CRCW04025K10JNED	Vishay-Dale		
R6	1	10k	RES, 10k ohm, 5%, 0.063W, 0402	0402	CRCW040210K0JNED	Vishay-Dale		
SH-J2, SH- J3, SH-J8, SH-J9, SH- J11	5	1x2	Shunt, 100mil, Gold plated, Black	Shunt	969102-0000-DA	3M	SNT-100-BK-G	Samtec
TP1, TP7, TP9	3	5001	Test Point, Black, Thru Hole Color Keyed	0.100 x 0.100 inch	5001	Keystone		
TP2, TP3, TP11, TP12	4	5002	Test Point, White, Thru Hole Color Keyed	0.100 x 0.100 inch	5002	Keystone		
TP4, TP5, TP6, TP8, TP10	5	5000	Test Point, Red, Thru Hole Color Keyed	0.100 x 0.100 inch	5000	Keystone		
U1	1	BQ27441DRZ-G1A	IC, Single-Cell Impedance Track Gas Gauge	QFN12	BQ27441DRZ-G1A	TI		None
FID1, FID2, FID3	0		Fiducial mark. There is nothing to buy or mount.	Fiducial	N/A	N/A		

Notes:

Unless otherwise noted in the Alternate PartNumber and/or Alternate Manufacturer columns, all parts may be substituted with equivalents.

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